

USB 2.0

**82C871
On-The-Go Controller**

Data Book

912-2003-001
Revision 1.1
25 March 2003

Copyright

Copyright © 2003 OPTi Technologies, Inc. All rights reserved. No part of this publication may be reproduced, transmitted, transcribed, stored in a retrieval system, or translated into any language or computer language, in any form or by any means, electronic, mechanical, magnetic, optical, manual, or otherwise, without the prior written permission of OPTi Technologies, Inc., 2362 Qume Drive, Suite B, San Jose, CA 95131.

Disclaimer

OPTi Technologies, Inc. makes no representations or warranties with respect to the design and documentation herein described and especially disclaims any implied warranties of merchantability or fitness for any particular purpose. Furthermore, OPTi Technologies, Inc. reserves the right to revise the design and associated documentation and to make changes from time to time in the content without obligation of OPTi Technologies, Inc. to notify any person of such revisions or changes.

Trademarks

OPTi and OPTi Technologies, Inc. are registered trademarks of OPTi Technologies, Inc. All other trademarks and copyrights are the property of their respective holders.

OPTi Technologies, Inc.
2362 Qume Drive, Suite B
San Jose, CA 95131
Tel: (408) 434-0880
Fax: (408) 434-0770
<http://www.opti-inc.com>

CONTENTS

1. DESCRIPTION	1
2. FEATURES	1
3. BLOCK DIAGRAM.....	2
4. PIN ASSIGNMENT.....	3
4.1 CSP Package.....	3
4.2 QFP Package.....	4
5. PIN DESCRIPTION.....	5
5.1 CPU Interface	5
5.2 USB Interface	6
5.3 System.....	7
5.4 Test Signals	7
5.5 Power Supply, GND, etc.	8
6. FUNCTIONAL DESCRIPTION.....	9
6.1 Host Controller (HC)	9
6.2 Peripheral Controller (PC).....	9
6.3 OTG Controller.....	9
6.4 HC/PC Common	9
6.5 USB Transceiver	9
6.6 Control Registers	9
6.7 FIFO Manager	10
6.8 FIFO SRAM	10
6.9 CPU Interface	10
6.10 DMA Handler	10
6.11 CLK Controller	10
6.12 Test Module	10
7. ELECTRICAL CHARACTERISTICS.....	11
7.1 Absolute Maximum Ratings	11
7.2 Recommended operating condition	11
7.3 DC Characteristics	12
7.4 AC Characteristics	15
7.4.1 Clock timing.....	15
7.4.2 CPU Interface Access Timing.....	17
7.4.3 DMA Timing.....	19
7.4.4 USB Interface Timing	27
8. EXTERNAL DIMENSIONS DRAWING	28
8.1 CSP Package.....	28
8.2 QFP Package.....	29
9. CONNECTION EXAMPLES.....	30
9.1 OTG Interface Pin Connection (Example).....	30
9.2 Clock Pin Connection (Example)	32
9.3 CPU Interface Pin Connection (Example).....	34
9.4 Power Supply and Ground Pin Connection (Example)	36
9.5 Test Pin Connection (Example).....	37

1 DESCRIPTION

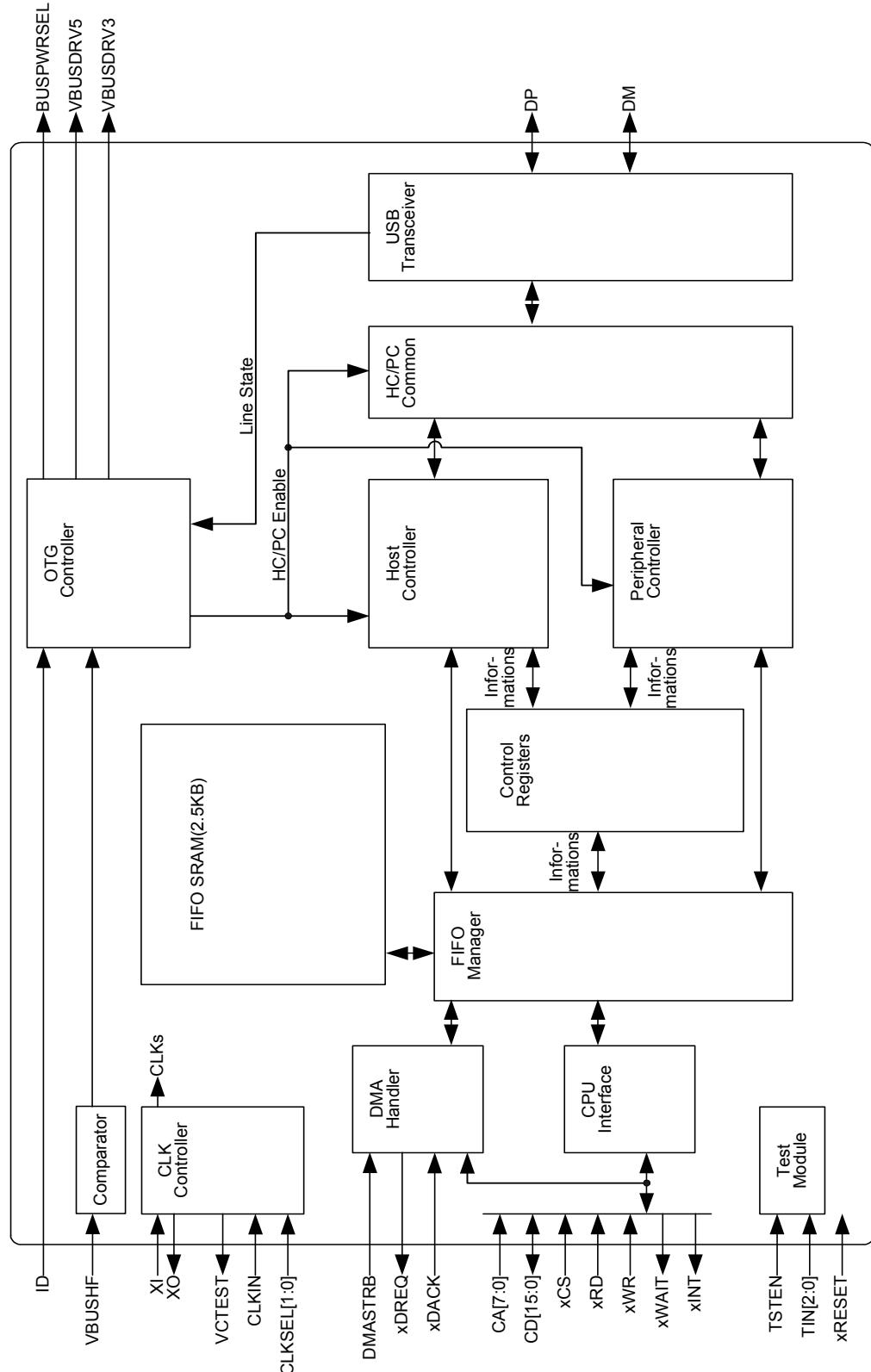
The 82C871 is an USB 2.0 compliant On-The-Go device controller LSI that supports Full Speed (12Mbps) mode. In addition to the Host and the Function functions, it integrates the On-The-Go function to a single chip, making the LSI a dual-role device.

It provides not only a general connectivity between the USB device and the PC, but also an unlimited connectivity between two USB devices.

2 FEATURES

- Integrates the Host, the Function and the On-The-Go functions into a single chip.
 - Compliant with On-The-Go (Supplement to the USB2.0) version 1.0.
 - Supports USB2.0 Full Speed (12Mbps) mode.
 - Equipped with one On-The-Go port.
 - Supports control, bulk, interrupt and Isochronous transfers.
 - Is a controller interface that achieves lower CPU load and high throughput during USB transfer.
 - Supports five general Endpoint and Endpoint 0.
 - Has built-in 2.5KByteFIFO for data transfer.
 - FIFO uses ring buffer method.
 - Installed with 16-bit width generic CPU Interface.
 - Operates as 16-bit width generic DMA slave (shares bus with CPU Interface).
 - Supports clock input 12 MHz oscillator (built-in oscillation circuit).
 - Has built-in multiplier PLL circuit.
 - Supports external clock input of 12MHz, 27MHz and 48MHz from the crystal oscillator.
 - Has low power consumption which is achieved through thorough clock control.
 - Is two-power operated (3.3 V and 2.5 V. I/O power supply: 3.3V, internal operation power: 2.5V).
 - 81-pin CSP package or 64-pin QFP package.
- ※ No anti-radiation design

3 BLOCK DIAGRAM



4 PIN ASSIGNMENT

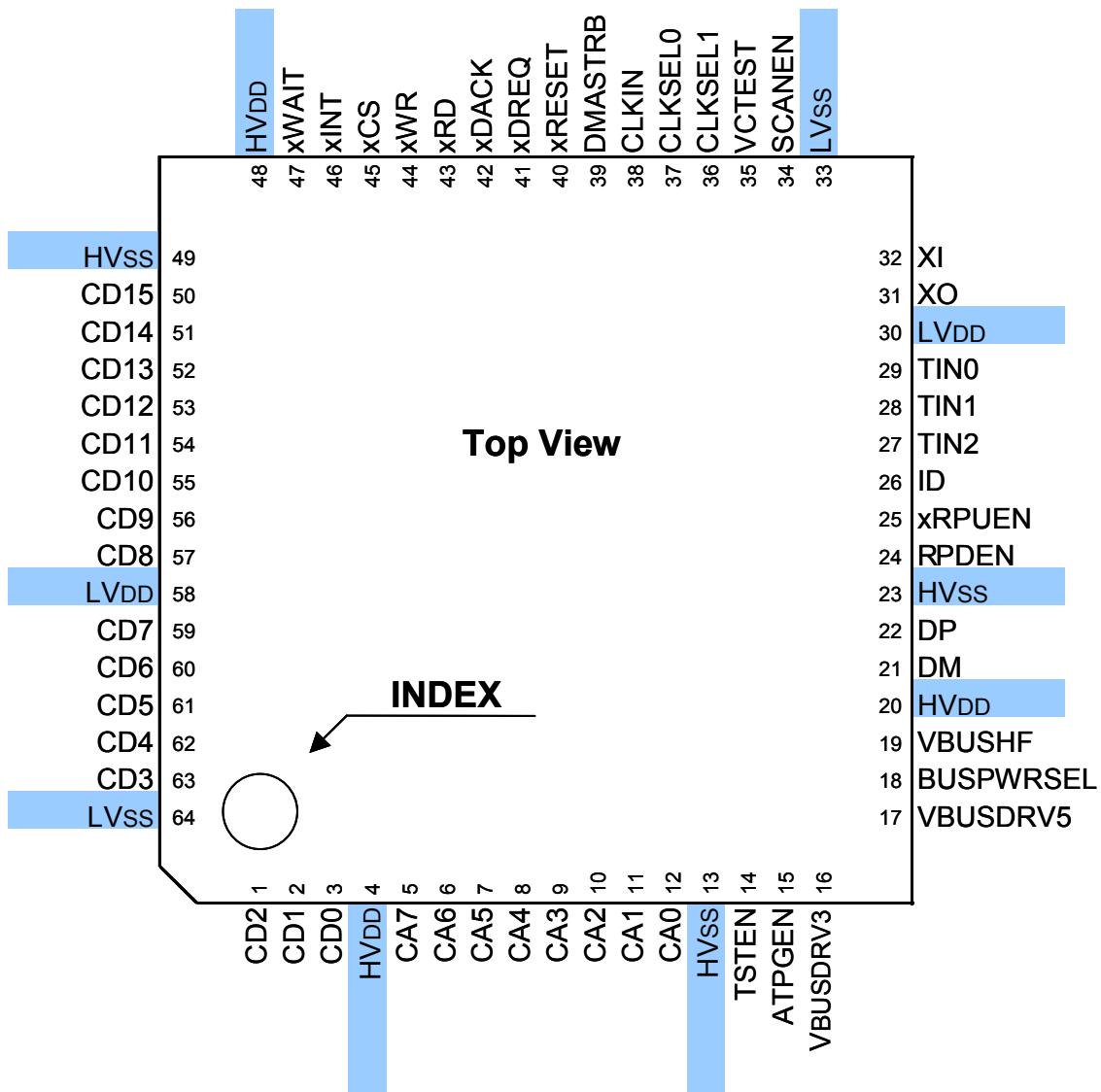
4.1 CSP Package

J	—	VBUS DRV5	VBUSHF	DM	RPDEN	ID	LVDD	XI	—
H	VBUS DRV3	HVss	BUS PWRSEL	DP	HVss	TIN2	XO	TIN0	LVss
G	TSTEN	ATPGEN	HVDD	—	TEST PAD0	TIN1	CLKSEL1	SCANEN	VCTEST
F	CA2	CA1	CA0	VTEST11	XRPUEN	—	—	CLKIN	CLKSEL0
E	CA3	CA4	CA5	VTEST01	—	COMPIN 22	DMA STRB	XRESET	XDREQ
D	CA7	CA6	—	—	—	COMPIN 10	XWR	XRD	XDACK
C	CD0	CD1	HVDD	CD6	CD10	—	CD13	XWAIT	XINT
B	CD2	CD5	CD3	CD7	CD9	CD11	CD15	XCS	HVDD
A	—	LVss	CD4	LVDD	CD8	CD12	CD14	HVss	—

1 2 3 4 5 6 7 8 9

Bottom View

4.2 QFP Package



5 PIN DESCRIPTION

5.1 CPU Interface

Symbol	Pin name	Pin number		Pin type	Description
		CSP	QFP		
DMASTRB	DMA Strobe	E7	39	I (Gated CMOS)	Strobe signal for burst DMA transfer. Connect to GND (HVss) when not in use.
xDREQ	DMA Request	E9	41	O (3-state 3mA)	DMA transfer request. Initial state is HiZ. Select either low active or high active from register setting.
xDACK	DMA Acknowledge	D9	42	I (Gated CMOS)	DMA transfer permission.
xRD	Read Strobe	D8	43	I (Gated CMOS)	CPU read strobe.
xWR	Write Strobe	D7	44	I (Gated CMOS)	CPU write strobe.
xCS	Chip Select	B8	45	I (CMOS)	Chip select signal.
xINT	Interrupt signal	C9	46	O (3-state 3mA)	Interruption signal to the CPU. Initial state is HiZ. Select either HiZ/0 or 1/0 from register setting.
xWAIT	Wait signal	C8	47	O (3-state 3mA)	Wait signal to the CPU. Initial state is HiZ. Select either HiZ/0 or 1/0 from register setting.
CD15 CD14 CD13 CD12 CD11 CD10 CD9 CD8 CD7 CD6 CD5 CD4 CD3 CD2 CD1 CD0	CPU Data	B7 A7 C7 A6 B6 C5 B5 A5 B4 C4 B2 A3 B3 B1 C2 C1	50 51 52 53 54 55 56 57 59 60 61 62 63 1 2 3	I/O (Gated CMOS 3mA)	CPU data bus. Initial state is Input mode. Outputs register data during read, and sets register data from the CPU during write. Shares with DMA data bus.
CA7 CA6 CA5 CA4 CA3 CA2 CA1 CA0	CPU Address	D1 D2 E3 E2 E1 F1 F2 F3	5 6 7 8 9 10 11 12	I (Gated CMOS)	CPU address bus. Specifies the register address.

5.2 USB Interface

Symbol	Pin name	Pin number		Pin type	Description
		CSP	QFP		
VBusDRV3	Vbus Drive	H1	16	O (3mA)	Enables VBUS3.3V drive. 0: disable, 1: enable Initial state is disable. Open when not in use.
VBusDRV5	Vbus Drive	J2	17	O (3mA)	Enables VBUS5V drive (Max. 8mA). 0: disable, 1: enable Initial state is disable.
BUSPWRSEL	Vbus Drive	H3	18	O (3mA)	Enables VBUS5V drive (over 8mA). 0: disable, 1: enable Initial state is disable.
COMPIN10	1.0V level Detection signal	D6	—	I (CMOS 120kΩ with pull down)	VBUS/2 level detection result (1.0V). 0:VBUS/2 < 1.0V, 1:VBUS/2 ≥ 1.0V Connect to GND when using internal comparator.
COMPIN22	2.2V level Detection signal	E6	—	I (CMOS 120kΩ with pull down)	VBUS/2 level detection result (2.2V). 0:VBUS/2 < 2.2V, 1:VBUS/2 ≥ 2.2V Connect to GND when using internal comparator.
DM	USB negative pole signal	J4	21	I/O (special)	USB data line D-
DP	USB positive pole signal	H4	22	I/O (special)	USB data line D+
RPDEN	Rpd Enable	J5	24	O (3mA)	Enable D+ pull down. 0: disable, 1: enable Open when internal resistor is not in use.
xRPUEN	Rpu Enable	F5	25	O (3mA)	Enable D+ pull up. 0: enable, 1: disable Open when internal resistor is not in use.
ID	ID signal	J6	26	I (CMOS Schmidt 120kΩ with pull up)	ID signal 0: A-Device, 1: B-Device
VBusHF	VBus/2	J3	19	I (special)	VBus/2 level Connect to GND when using external comparator.

5.3 System

Symbol	Pin name	Pin number		Pin type	Description
		CSP	QFP		
XO	Oscillator output	H7	31	O (special)	Output for built-in oscillation circuit. Open when not in use.
XI	Oscillator input	J8	32	I (special)	Input for built-in oscillation circuit. Connect to GND (LVss) through pull down resistor when not in use.
VCTEST	PLL filter test	G9	35	O (special)	PLL filter circuit test pin
CLKSEL1 CLKSEL0	Clock selection	G7 F9	36 37	I (CMOS Schmidt)	Selection pin for oscillator or external clock use. CLKSEL[1:0] Uses 00: 12MHz oscillator. Uses 01: external 27MHz clock input. Uses 10: external 48MHz clock input. 11: not used.
CLKIN	External clock input	F8	38	I (TTL)	External clock input. Connect to GND (HVss) when not in use. When using external clock input, clock supply should be stable before reset release.
XRESET	Chip reset	E8	40	I (CMOS Schmidt 120kΩ with pull up)	Chip reset

5.4 Test Signals

Symbol	Pin name	Pin number		Pin type	Description
		CSP	QFP		
TIN2 TIN1 TIN0	Test mode	H6 G6 H8	27 28 29	I (CMOS Schmidt 120kΩ with pull down)	Mode setting input pin 000: Normal Others: Internal test mode Connect to GND (HVss) during normal use.
TSTEN	Test enable	G1	14	I (TEST I/O)	Test enable pin 0: Normal, 1: Test Connect to GND (HVss) during normal use.
TESTPAD0	Internal pull up resistor 2 measurement pin	G5	—	O (special)	Test pin Open when not in use.
VTEST01	Reference voltage monitor	E4	—	O (special)	Test pin Open when not in use.

VTEST11	Reference voltage monitor	F4	—	O (special)	Test pin Open when not in use.
ATPGEN	Test ATPG	G2	15	I (CMOS Schmidt 120kΩ with pull down)	Test pin Connect to GND (HVss) during normal use.
SCANEN	Test SCAN	G8	34	I (CMOS Schmidt 120kΩ with pull down)	Test pin Connect to GND (HVss) during normal use.

5.5 Power Supply, GND, etc.

Symbol	Pin name	Pin number		Pin type	Description
		CSP	QFP		
HVDD	Power Supply for I/O Part	C3 G3 B9	4 20 48	P	3.3V power supply pin for I/O
HVss	Ground for I/O Part	H2 H5 A8	13 23 49	P	Ground pin for I/O
LVDD	Power Supply for Logic part	J7 A4	30 58	P	2.5V power supply pin for internal use
LVss	Ground for Logic part	H9 A2	33 64	P	Ground pin for internal use
NC	None Connect	C6 D3 D4 D5 E5 F6 F7 G4 A1 A9 J1 J9	—	—	Unused pin Open during normal use.

6 FUNCTIONAL DESCRIPTION

6.1 Host Controller (HC)

- Arbitrates multiple transactions, manages time frame, schedules transfers and manages retransmission.
- Manages transactions.
- Generates/disassembles packets.
- Indicates suspend/resume reset state generation.

6.2 Peripheral Controller (PC)

- Manages end point operation information via register.
- Manages transactions.
- Generates/disassembles packets.
- Indicates remote wakeup signal generation.

6.3 OTG Controller

- Monitors USB data line state (including connect and disconnect).
- Monitors VBUS level.
- Monitors ID.
- Controls VBUS drive/stop, pull up/pull down resistor (D+) connect/disconnect and HC/PC enable and disable for OTG operation.

6.4 HC/PC Common

- Indicates USB data line state generation.
- Switches connection between HC or the PC for the USB Transceiver.

6.5 USB Transceiver

- Processes parallel/serial conversion.
- Processes bit stuffing/unstuffing.
- Performs NRZI encode/decode process.
- Sends and receives USB data signals.
- Generates USB data line state.

6.6 Control Registers

- Holds register group related to transaction and end point control.

6.7 FIFO Manager

- Manages FIFO access address of the CPU/DMA and USB.
- Manages FIFO access arbitration of the CPU/DMA and USB.

6.8 FIFO SRAM

- Uses it as FIFO for data transfer (total: 2.5KByte).

6.9 CPU Interface

- Controls PIO transfer.
- Generates interrupt signal to the CPU.

6.10 DMA Handler

- Controls DMA transfer (DMA slave).

6.11 CLK Controller

- Generates various clocks used internally from the multiplier PLL (when an oscillator is used) or from the external input clock.
- Controls clock operation that is used per block.

6.12 Test Module

- Performs internal operation verification test.

7 ELECTRICAL CHARACTERISTICS

7.1 Absolute Maximum Ratings

(V _{SS} =0V)			
Item	Symbol	Rated values	Unit
Power supply voltage	HV _{DD} *	-0.3 to +4.0	V
	LV _{DD} *	-0.3 to +3.0	V
Input voltage	HVI	-0.3 to HV _{DD} +0.5	V
	LVI	-0.3 to LV _{DD} +0.5	V
Output voltage	HVO	-0.3 to HV _{DD} +0.5	V
	LVO	-0.3 to LV _{DD} +0.5	V
Output current/pin	I _{OUT}	±30	mA
Storage temperature	T _{STG}	-65 to +150	°C

*HV_{DD} ≥ LV_{DD}

7.2 Recommended operating condition

Item	Symbol	Min.	Typ.	Max.	Unit
Power supply voltage	HV _{DD}	3.00	3.30	3.60	V
	LV _{DD}	2.30	2.50	2.70	V
Input voltage	HVI	V _{SS}	—	HV _{DD}	V
	LVI	V _{SS}	—	LV _{DD}	V
Ambient temperature	T _a	-20	25	85	°C

7.3 DC Characteristics

DC Characteristics (on recommended operating condition) (1)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Current consumption						
Power supply current	IDDH	HV _{DD} = 3.6V	—	—	20	mA
	IDDL	LV _{DD} = 2.7V	—	—	40	mA
Static current (static current between HV _{DD} and V _{SS})						
Power supply current	IDDSH	V _{IN} = HV _{DD} or LV _{DD} or V _{SS} HV _{DD} = 3.6V LV _{DD} = 2.7V	—	—	30	μA
Static current (static current between LV _{DD} and V _{SS})						
Power supply current	IDDSL	V _{IN} = HV _{DD} or LV _{DD} or V _{SS} HV _{DD} = 3.6V LV _{DD} = 2.7V	—	—	120	μA
Input leak						
Input leak current	I _L	V _{IN} = HV _{DD} or LV _{DD} or V _{SS} HV _{DD} = 3.6V LV _{DD} = 2.7V HVIH = HV _{DD} LVIL = LV _{DD} VIL = V _{SS}	-5	—	5	μA

DC Characteristics (on recommended operating condition) (2)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Input characteristics (CMOS)	Pin name: CA7..CA0, CD15..CD0, TESTEN,xCS, xDACK, xRD, xWR, DMASTRB, COMPIN10, COMPIN22					
HIGH level input voltage	VIH1H	HVDD = 3.6V	2.2	—	—	V
LOW level input voltage	VIL1H	HVDD = 3.0V	—	—	0.8	V
Schmitt input characteristics (CMOS)	Pin name: ID, xRESET, CLKSEL1, CLKSEL0, TIN2, TIN1, TIN0, SCANEN, ATPGEN					
HIGH level trigger voltage	VT1+	HVDD = 3.6V	1.4	—	2.7	V
LOW level trigger voltage	VT1-	HVDD = 3.0V	0.6	—	1.8	V
Hysteresis voltage	ΔV1	HVDD = 3.0V	0.3	—	—	V
Input characteristics (LVTTL)	Pin name: CLKIN					
HIGH level input voltage	VIH2H	HVDD = 3.6V	2.0	—	—	V
LOW level input voltage	VIL2H	HVDD = 3.0V	—	—	0.8	V
Schmitt input characteristics (USB: FS)	Pin name: DP, DM					
HIGH level trigger voltage	VT+(USB)	HVDD = 3.6V	1.1	—	1.8	V
LOW level trigger voltage	VT-(USB)	HVDD = 3.0V	1.0	—	1.5	V
Hysteresis voltage	ΔV(USB)	HVDD = 3.0V	0.1	—	—	V
Input characteristics (USB: FS difference input)	Pin name: DP and DM pair					
Sensitivity of difference input	VDS(USB)	HVDD = 3.0V Difference input voltage 0.8V to 2.5V	—	—	0.2	V
Input pull up characteristics	Pin name: ID, xRESET					
Pull up resistance value	RPU2	HVDD = 3.3V VIH = VSS	60	120	288	kΩ
Input pull down characteristics	Pin name: SCANEN, ATPGEN, TIN2, TIN1, TIN0, COMPIN10, COMPIN22					
Pull down resistance value	RPD2	HVDD = 3.3V VIH = VSS	60	120	288	kΩ

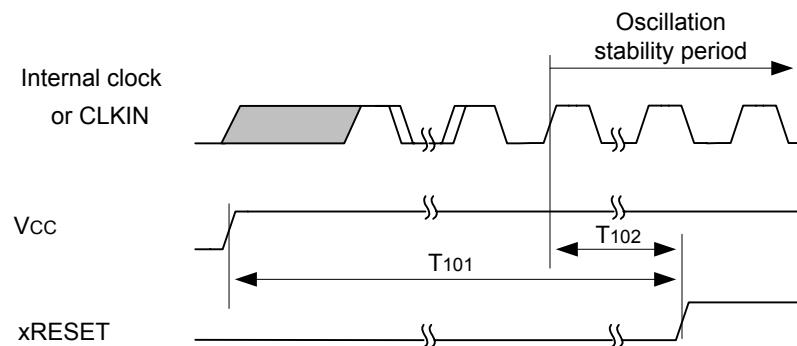
DC Characteristics (on recommended operating condition) (3)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Output characteristics	Pin name: xRPUEN, RPDEN, VBUSDRV3, VBUSDRV5, BUSBWRSEL, CD15..CD0, xINT, xWAIT, xDREQ,					
HIGH level output voltage	V _{OH1H}	H _{VDD} = 3.0V I _{OH} = -3mA	V _{DD} -0.4	—	—	V
LOW level output voltage	V _{OL1H}	H _{VDD} = 3.0V I _{OL} = 3mA	—	—	0.4	V
Output characteristics (USB: FS)	Pin name: DP, DM					
HIGH level output voltage	V _{OH(USB)}	H _{VDD} = 3.0V	2.8	—	—	V
LOW level output voltage	V _{OL(USB)}	H _{VDD} = 3.6V	—	—	0.3	V
Output characteristics	Pin name: xRPUEN, RPDEN, VBUSDRV3, VBUSDRV5, BUSBWRSEL, CD15..CD0, xINT, xWAIT, xDREQ					
OFF-STATE leak current	I _{OZ1H}	H _{VDD} = 3.6V V _{OH} = V _{DD} V _{OL} = V _{SS}	-5	—	5	μA
Pin capacity	Pin name: all input pins					
Input pin capacity	C _I	f = 1MHz V _{DD} = V _{SS}	—	—	8	pF
Pin capacity	Pin name: all output pins					
Output pin capacity	C _O	f = 1MHz V _{DD} = V _{SS}	—	—	8	pF
Pin capacity	Pin name: all input and output pins					
Input and output pin capacity	C _{IO}	f = 1MHz V _{DD} = V _{SS}	—	—	8	pF

7.4 AC Characteristics

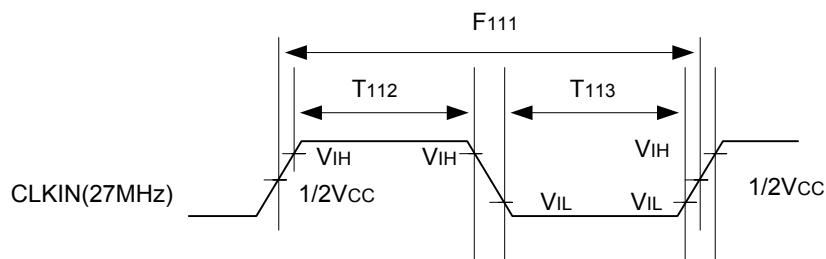
7.4.1 Clock timing

7.4.1.1 Oscillation Stability Time During Power On



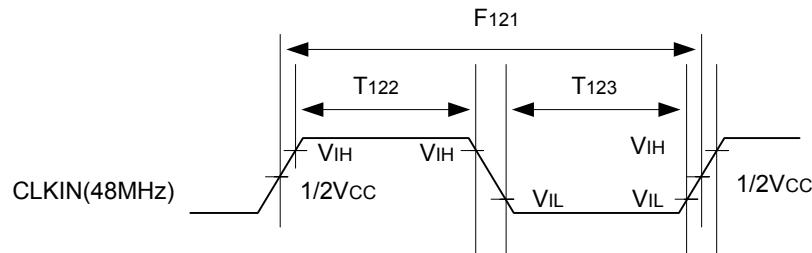
Symbol	Description	Min.	Typ.	Max.	Unit
T101	Oscillation stability time during power on	10	—	—	ms
T102	xRESET setup time	200	—	—	μs

7.4.1.2 CLKIN (27MHz) Clock Input Timing



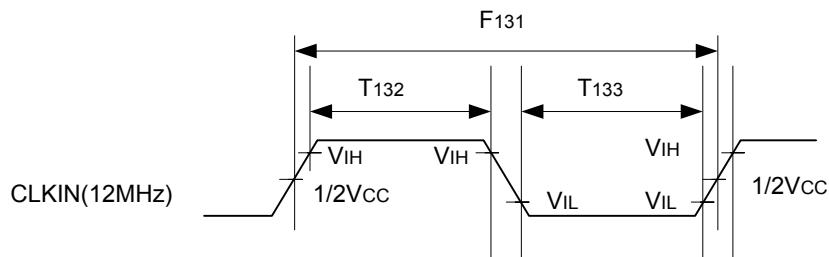
Symbol	Description	Min.	Typ.	Max.	Unit
F111	Clock input frequency	26.9973	27	27.0027	MHz
T112	Clock input HIGH level pulse width	12	—	23	ns
T113	Clock input LOW level pulse width	12	—	23	ns

7.4.1.3 CLKIN (48MHz) Clock Input Timing



Symbol	Description	Min.	Typ.	Max.	Unit
F_{121}	Clock input frequency	47.9952	48	48.0048	MHz
T_{122}	Clock input HIGH level pulse width	7	—	13	ns
T_{123}	Clock input LOW level pulse width	7	—	13	ns

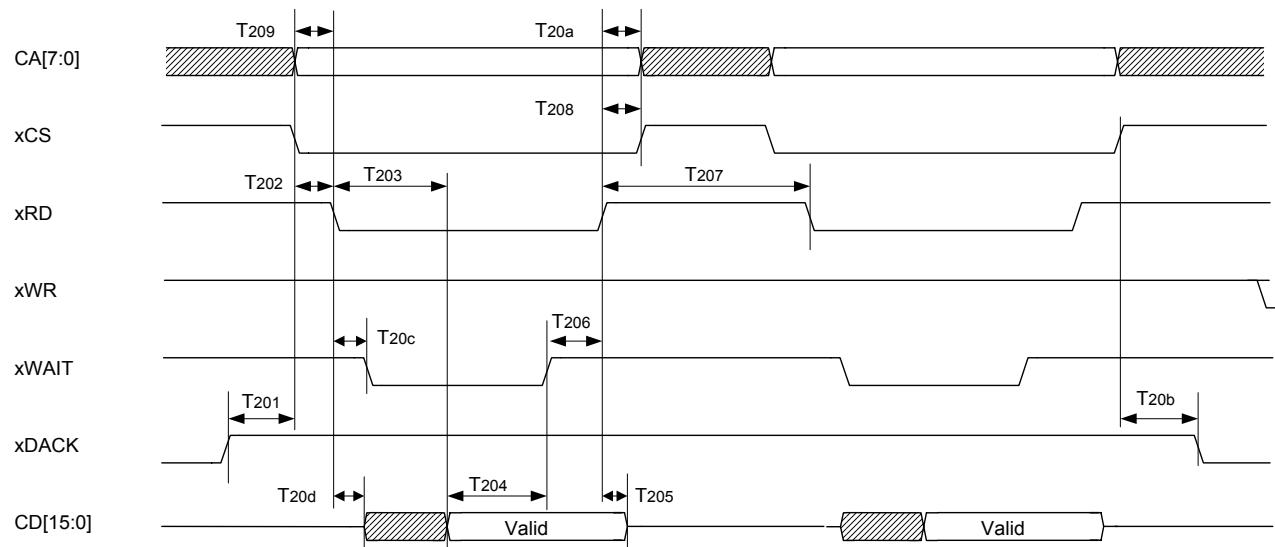
7.4.1.4 CLKIN (12MHz) Clock Input Timing



Symbol	Description	Min.	Typ.	Max.	Unit
F_{131}	Clock input frequency	11.9988	12	12.0012	MHz
T_{132}	Clock input HIGH level pulse width	28	—	52	ns
T_{133}	Clock input LOW level pulse width	28	—	52	ns

7.4.2 CPU Interface Access Timing

7.4.2.1 Register Read Timing

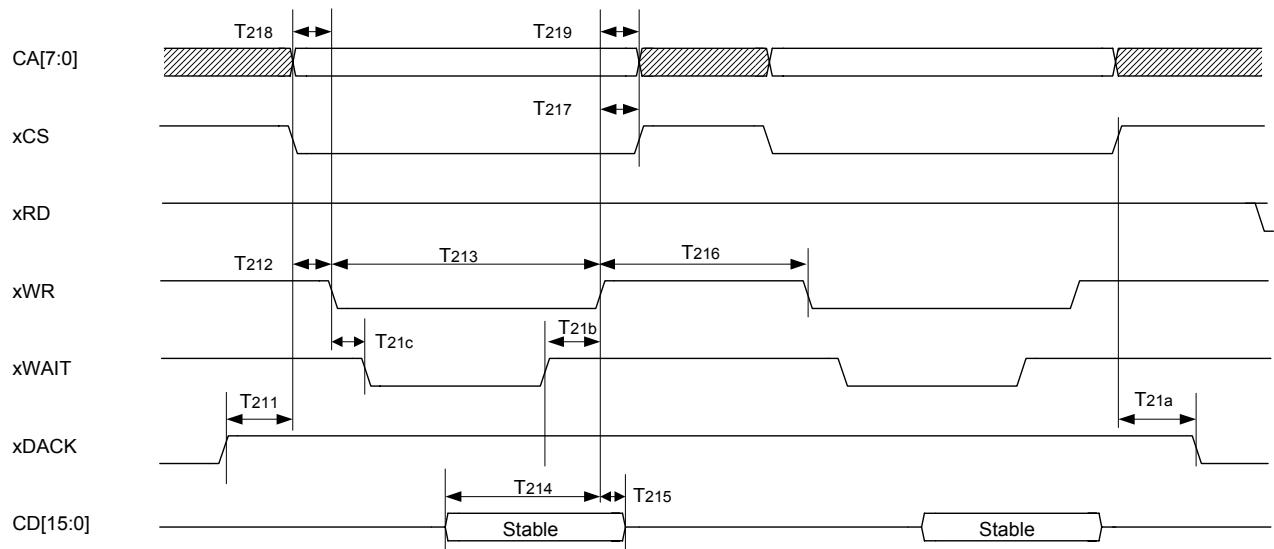


Symbol	Description	Min.	Typ.	Max.	Unit
T201	xCS assert time for xDACK negate	10	—	—	ns
T202	xRD assert time for xCS assert	0	—	—	ns
T203	CD output delay time (note 1) for xRD assert	42	—	62.5	ns
T204	xWAIT negate time for CD output	20	—	22	ns
T205	CD output hold time for xRD negate	2.5	—	18	ns
T206	xRD negate time for xWAIT negate	0	—	—	ns
T207	xRD negate period	42	—	—	ns
T208	xCS negate time for xRD negate	0	—	—	ns
T209	CA setup time for xRD assert	0	—	—	ns
T20a	CA hold time for xRD negate	0	—	—	ns
T20b	xDACK assert time for xCS negate	10	—	—	ns
T20c	xWAIT assert time for xRD assert	—	—	8	ns
T20d	CD bus valid delay time for xRD assert	—	—	8	ns

(Note 1)

This is a regulation during normal register access (except for access to FIFO forCPU register). During access to FIFO forCPU register, the time to data output is delayed depending on the state of access contention to internal FIFO memory.

7.4.2.2 Register Write Timing



Symbol	Description	Min.	Typ.	Max.	Unit
T211	xCS assert time for xDACK negate	10	—	—	ns
T212	xWR assert time for xCS assert	0	—	—	ns
T213	xWR assert pulse width	32	—	—	ns
T214	CD setup time for xWR negate	10	—	—	ns
T215	CD hold time for xWR negate	0	—	—	ns
T216	xWR negate period	42	—	—	ns
T217	xCS negate time for xWR negate	0	—	—	ns
T218	CA setup time for xWR assert	0	—	—	ns
T219	CA hold time for xWR negate	0	—	—	ns
T21a	xDACK assert time for xCS negate	10	—	—	ns
T21b	xWR negate time for xWAIT negate	0	—	—	ns
T21c	xWAIT assert time for xWR assert (Note 2)	—	—	8	ns

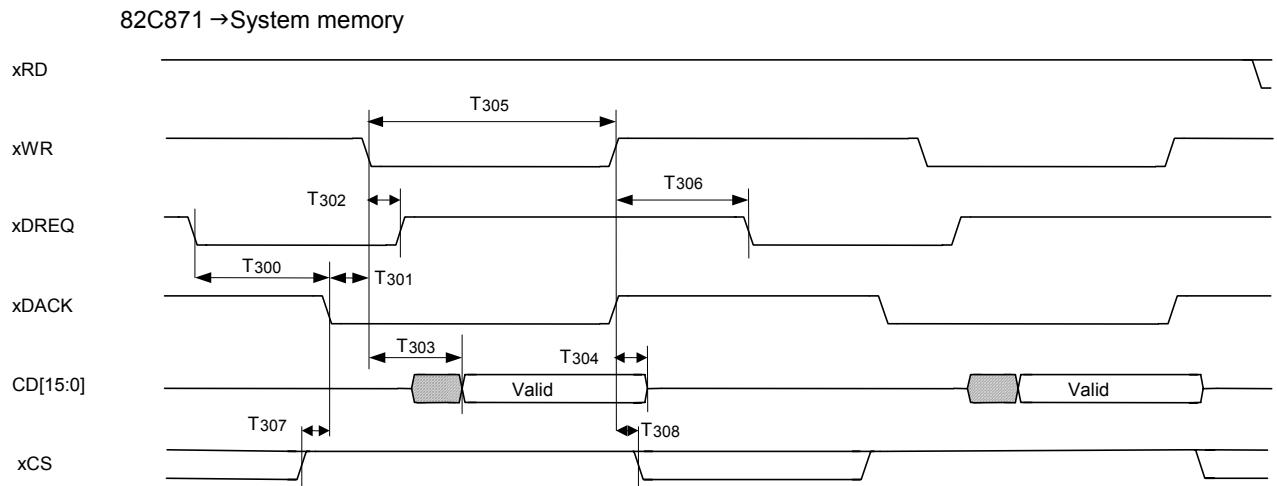
(Note 2)

xWAIT is not output for normal register access.

It may be output when there is successive access to FIFOforCPU register.

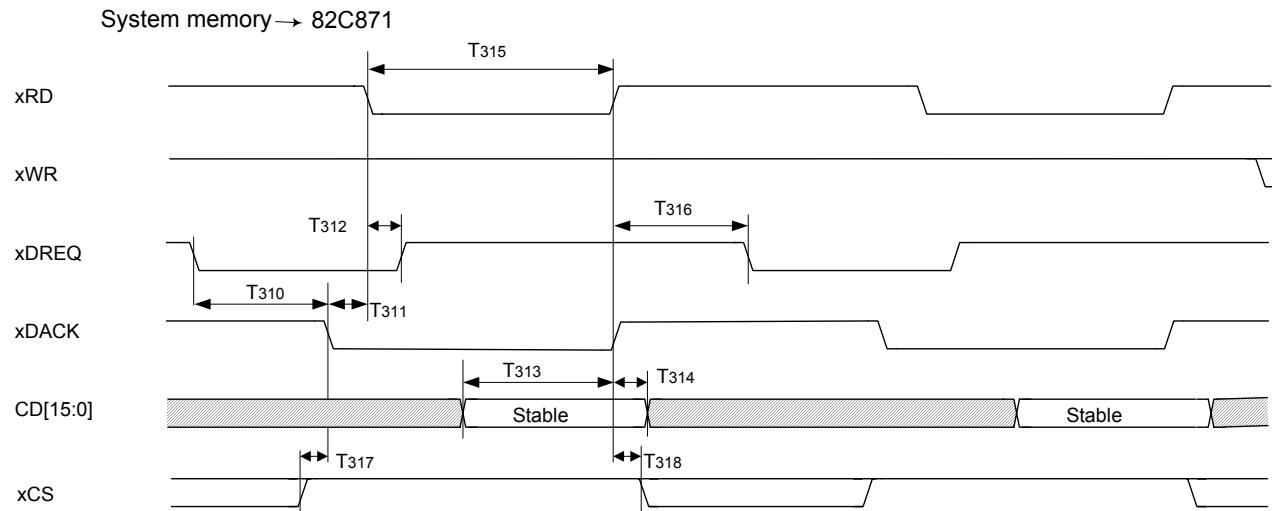
7.4.3 DMA Timing

7.4.3.1 xRD/xWR Strobe Mode (DMAOUT)



Symbol	Description	Min.	Typ.	Max.	Unit
T300	xDACK assert time for xDREQ assert	0	—	—	ns
T301	xWR assert time for xDACK assert	0	—	—	ns
T302	xDREQ negate time for xWR assert	—	—	10	ns
T303	Data output delay time for xWR assert	—	—	8	ns
T304	Data hold time for xWR negate	2	—	—	ns
T305	xWR assert pulse width	42	—	—	ns
T306	xDREQ assert time for xWR negate	160	—	—	ns
T307	xDACK assert time for xCS negate	0	—	—	ns
T308	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.2 xRD/xWR Strobe Mode (DMAIN)

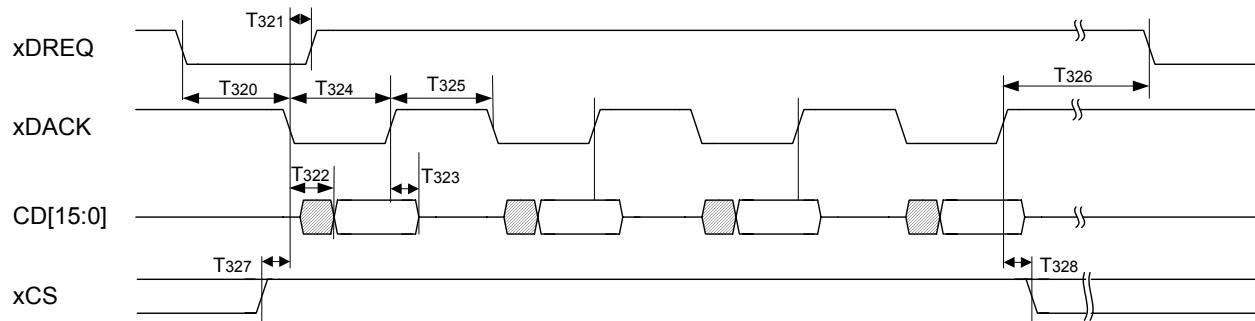


Symbol	Description	Min.	Typ.	Max.	Unit
T310	xDACK assert time for xDREQ assert	0	—	—	ns
T311	xRD assert time for xDACK assert	0	—	—	ns
T312	xDREQ negate time for xRD assert	—	—	10	ns
T313	Data setup time for xRD negate	10	—	—	ns
T314	Data hold time for xRD negate	0	—	—	ns
T315	xRD assert pulse width	42	—	—	ns
T316	xDREQ assert time for xRD negate	160	—	—	ns
T317	xDACK assert time for xCS negate	0	—	—	ns
T318	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.3 DACK Strobe Mode (DMAOUT)

82C871→System memory

BurstLength=4

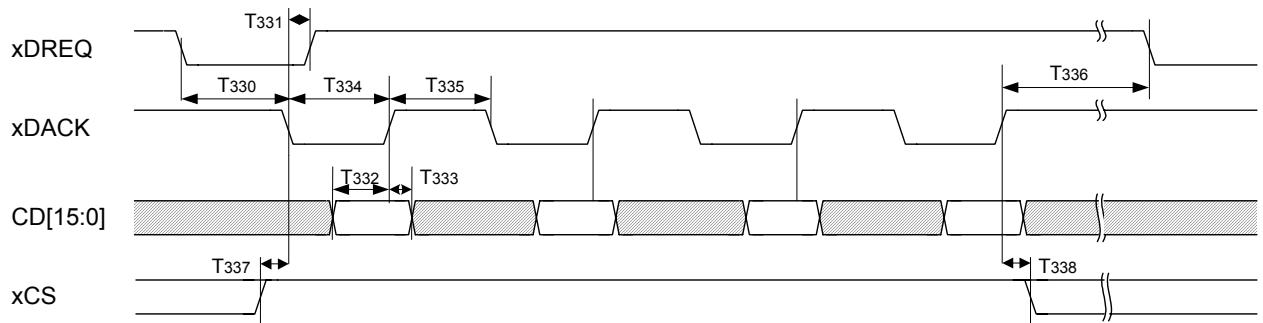


Symbol	Description	Min.	Typ.	Max.	Unit
T320	xDACK assert time for xDREQ assert	0	—	—	ns
T321	xDREQ negate time for xDACK assert	—	—	10	ns
T322	Data output delay time for xDACK assert	—	—	7	ns
T323	Data hold time for xDACK negate	2	—	—	ns
T324	xDACK assert pulse width	42	—	—	ns
T325	xDACK negate pulse width	42	—	—	ns
T326	xDREQ assert time for xDACK negate	160	—	—	ns
T327	xDACK assert time for xCS negate	0	—	—	ns
T328	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.4 DACK Strobe Mode (DMAIN)

System memory → 82C871

BurstLength=4

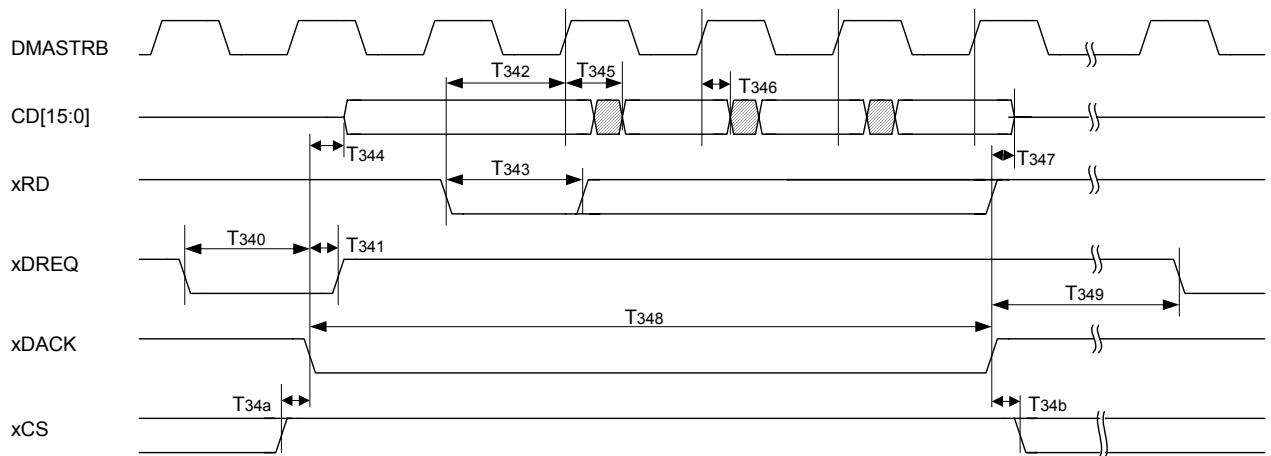


Symbol	Description	Min.	Typ.	Max.	Unit
T330	xDACK assert time for xDREQ assert	0	—	—	ns
T331	xDREQ negate time for xDACK assert	—	—	10	ns
T332	Data setup time for xDACK negate	10	—	—	ns
T333	Data hold time for xDACK negate	0	—	—	ns
T334	xDACK assert pulse width	42	—	—	ns
T335	xDACK negate pulse width	42	—	—	ns
T336	xDREQ assert time for xDACK negate	160	—	—	ns
T337	xDACK assert time for xCS negate	0	—	—	ns
T338	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.5 DMASTRB SDRAM Mode (DMAOUT)

82C871 → System memory(SDRAM)

DOUTLatency =0, BurstLength=4

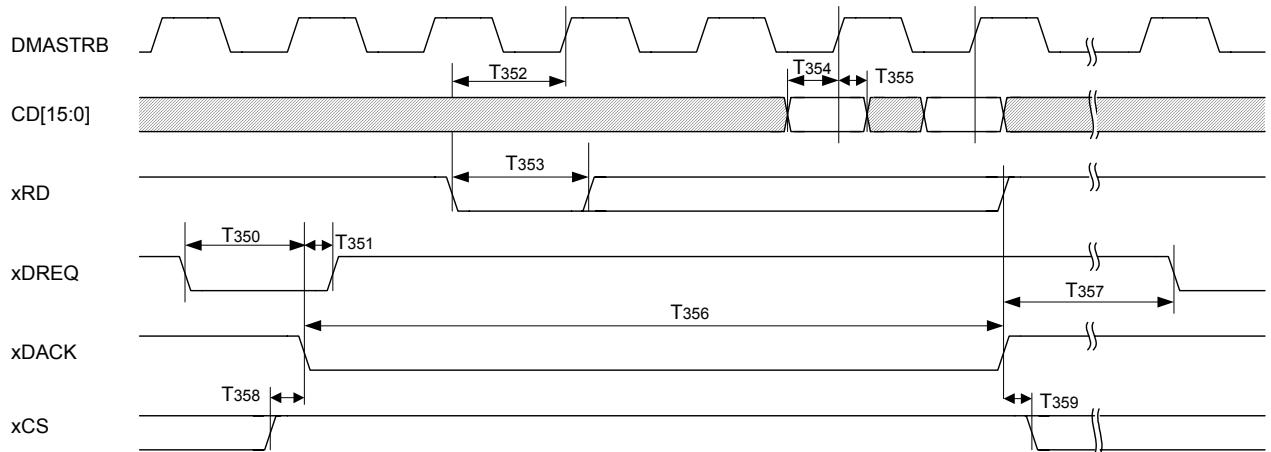


Symbol	Description	Min.	Typ.	Max.	Unit
T340	xDACK assert time for xDREQ assert	0	—	—	ns
T341	xDREQ negate time for xDACK assert	—	—	10	ns
T342	DMASTRB valid edge time for xRD (to CAS) assert	3	—	—	ns
T343	xRD (to CAS) assert pulse width (DMASTRB)	1T	—	—	ns
T344	Data output delay time for xDACK assert	—	—	7	ns
T345	Data output delay time for DMASTRB valid edge	—	—	9	ns
T346	Data hold time for DMASTRB valid edge	4	—	—	ns
T347	Data hold time for xDACK negate	2	—	—	ns
T348	xDACK assert pulse width	42	—	—	ns
T349	xDREQ assert time for xDACK negate	160	—	—	ns
T34a	xDACK assert time for xCS negate	0	—	—	ns
T34b	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.6 DMASTRB SDRAM Mode (DMAIN)

System memory(SDRAM) → 82C871

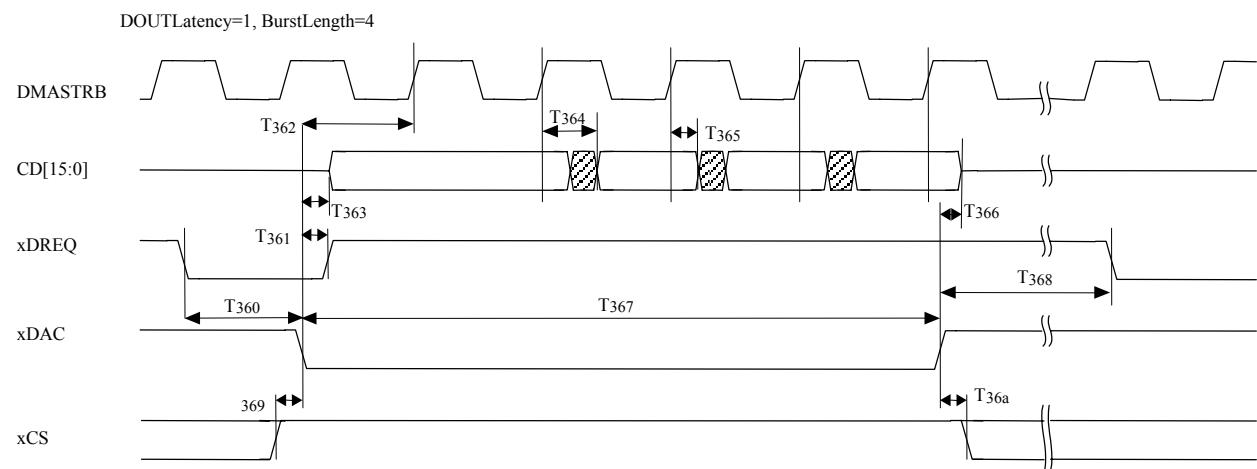
DINLatency(CL)=2, BurstLength=2



Symbol	Description	Min.	Typ.	Max.	Unit
T350	xDACK assert time for xDREQ assert	0	—	—	ns
T351	xDREQ negate time for xDACK assert	—	—	10	ns
T352	DMASTRB valid edge time for xRD (to CAS) assert	3	—	—	ns
T353	xRD (to CAS) assert pulse width	1T (DMASTRB)	—	—	ns
T354	Data setup time for DMASTRB valid edge	10	—	—	ns
T355	Data hold time for DMASTRB valid edge	0	—	—	ns
T356	xDACK assert pulse width	42	—	—	ns
T357	xDREQ assert time for xDACK negate	160	—	—	ns
T358	xDACK assert time for xCS negate	0	—	—	ns
T359	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.7 DMASTRB General Mode (DMAOUT)

82C871 → System

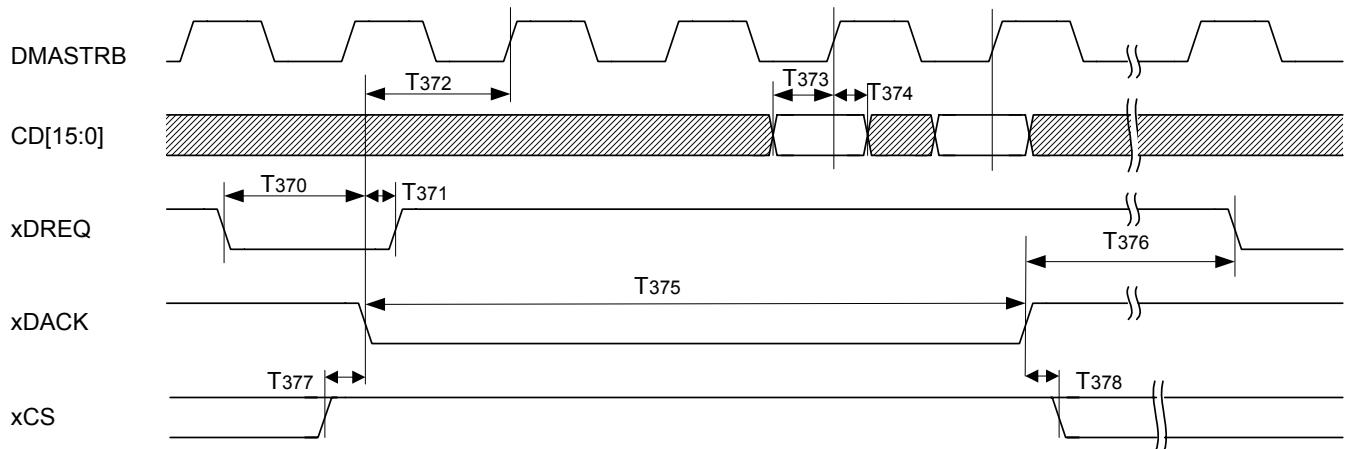


Symbol	Description	Min.	Typ.	Max.	Unit
T360	xDACK assert time for xDREQ assert	0	—	—	ns
T361	xDREQ negate time for xDACK assert	—	—	10	ns
T362	DMASTRB valid edge time for xDACK assert	3	—	—	ns
T363	Output data delay time for xDACK assert	—	—	7	ns
T364	Output data delay time for DMASTRB valid edge	—	—	9	ns
T365	Output data hold time for DMASTRB valid edge	4	—	—	ns
T366	Data hold time for xDACK negate	2	—	—	ns
T367	xDACK assert pulse width	42	—	—	ns
T368	xDREQ assert time for xDACK negate	160	—	—	ns
T369	xDACK assert time for xCS negation	0	—	—	ns
T36a	xCS assert time for xDACK negate	0	—	—	ns

7.4.3.8 DMASTRB General Mode (DMAIN)

System memory → 82C871

DINLatency=2, BurstLength=2



Symbol	Description	Min.	Typ.	Max.	Unit
T370	xDACK assert time for xDREQ assert	0	—	—	ns
T371	xDREQ negate time for xDACK assert	—	—	10	ns
T372	DMASTRB valid edge time for xDACK assert	3	—	—	ns
T373	Data setup time for DMASTRB valid edge	10	—	—	ns
T374	Data hold time for DMASTRB valid edge	0	—	—	ns
T375	xDACK assert pulse width	42	—	—	ns
T376	xDREQ assert time for T376xDACK negate	160	—	—	ns
T377	xDACK assert time for xCS negate	0	—	—	ns
T378	xCS assert time for xDACK negate	0	—	—	ns

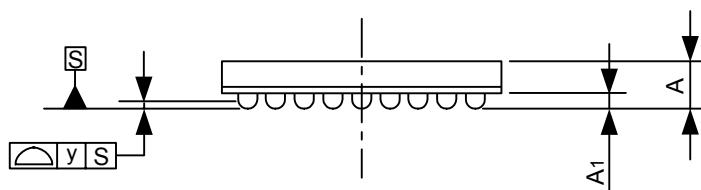
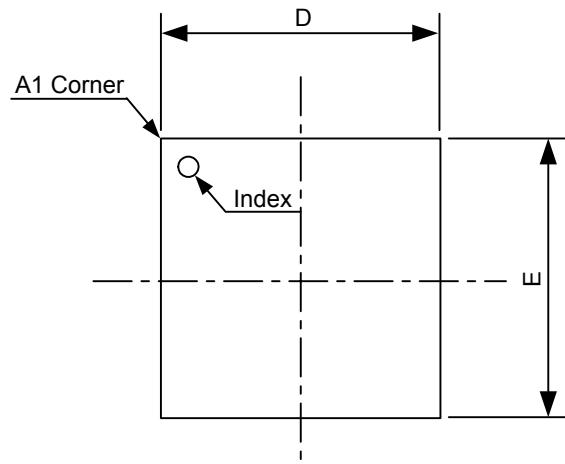
7.4.4 USB Interface Timing

The 82C871 conforms to USB 2.0 standard.

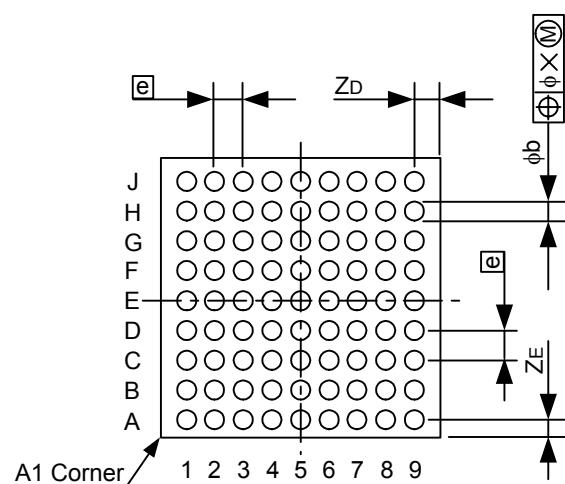
8 8. EXTERNAL DIMENSIONS DRAWING

8.1 8.1 CSP Package

Top View



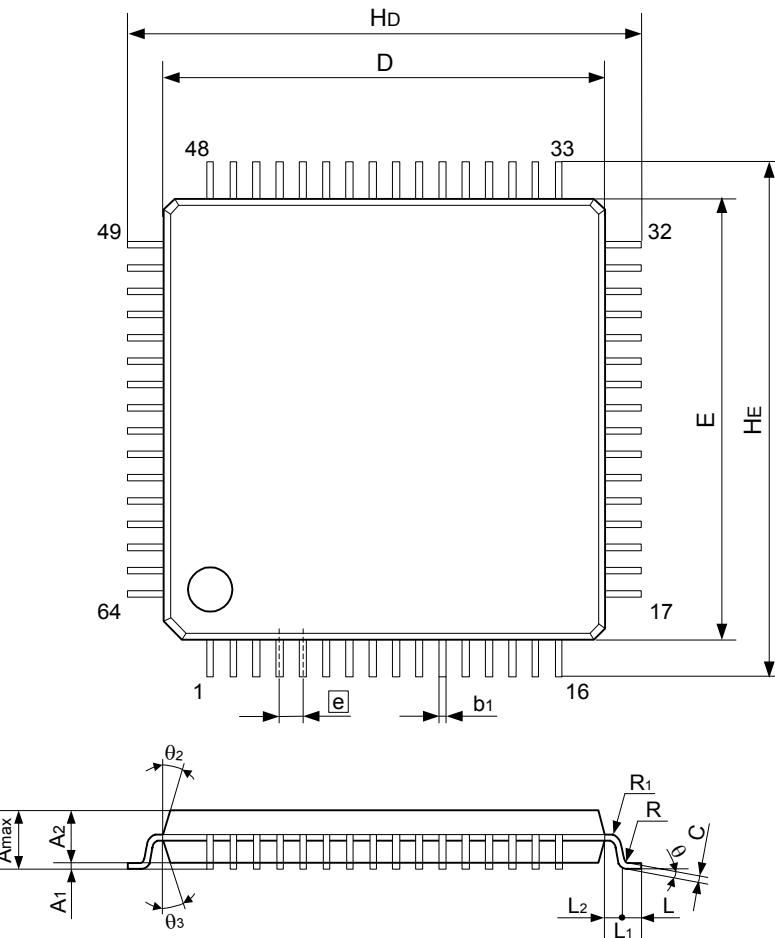
Bottom View



Symbol	Dimension in Millimeters		
	Min.	Nom.	Max.
D	7.80	8.0	8.2
E	7.80	8.0	8.2
A			1.20
A_1	0.25	0.30	0.35
e		0.80	
b	0.38	0.43	0.48
X			0.08
Y			0.10
Z_D		0.80	
Z_E		0.80	

1 = 1mm

8.2 QFP Package



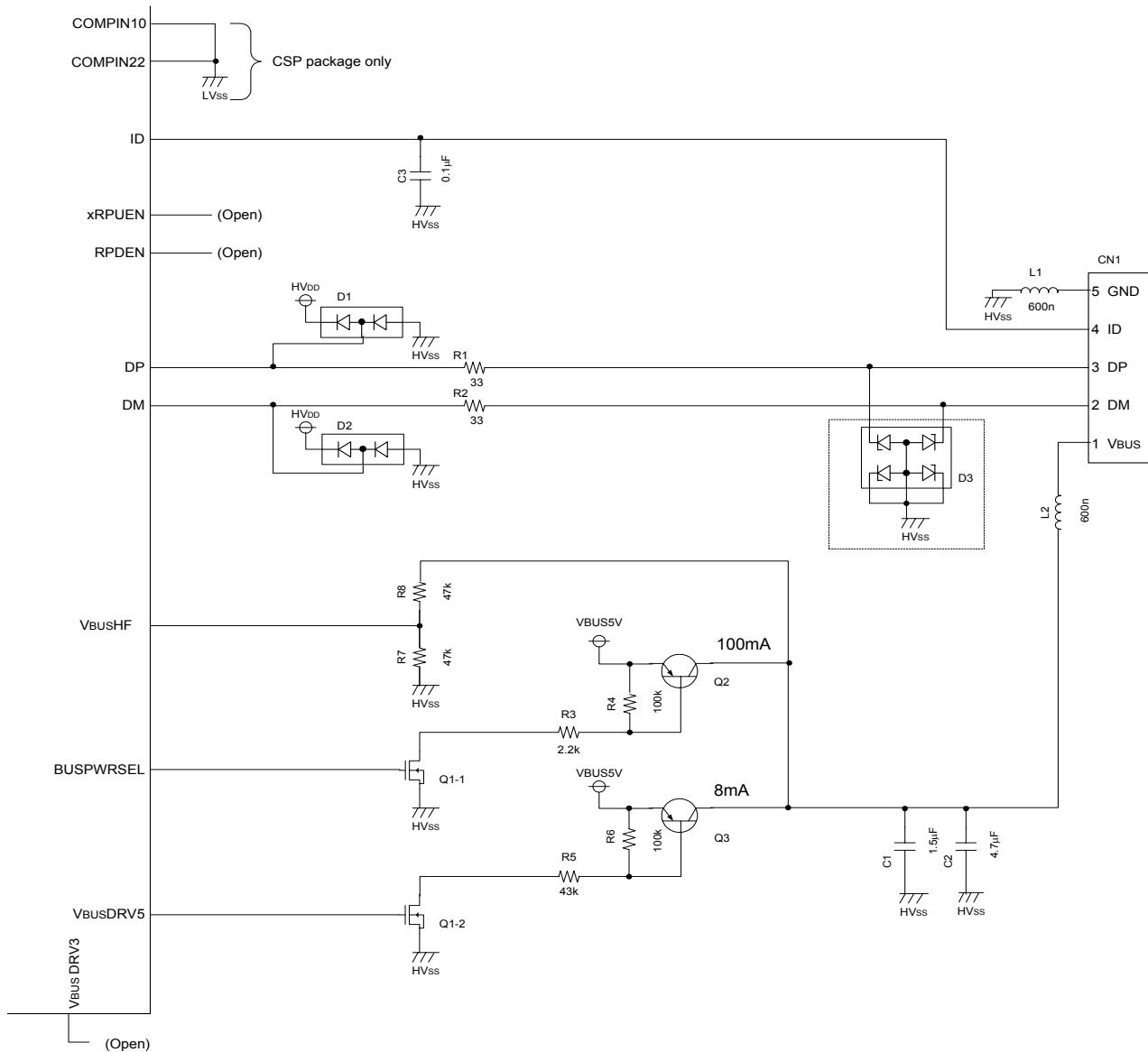
Symbol	Dimension in Millimeters		
	Min.	Nom.	Max.
E	9.9	10	10.1
D	9.9	10	10.1
A_{max}			1.7
A_1		0.1	
A_2	1.3	1.4	1.5
e		0.5	
b_1	0.13	0.18	0.28
C_1	0.1	0.125	0.175
θ	0°		10°
L	0.3	0.5	0.7
L_1		1	
L_2		0.5	
H_E	11.6	12	12.4
H_D	11.6	12	12.4
θ_2		12°	
θ_3		12°	
R		0.2	
R_1		0.2	

9 CONNECTION EXAMPLES

Above is the connection example (reference) for the external peripheral circuitry.

(Note) The connection example is for reference only. It does not guarantee operation in your product.
Users should examine the details of the circuit structure and select parts.

9.1 OTG Interface Pin Connection (Example)



(Note on connection)

- In order to protect the LSI from static electricity, set D1 and D2 diode protection circuits. Select the diodes according to their characteristics and ratings.
- For further protection from static electricity, use the D3 diode.
- Wire the DP and DM lines so that they are of the same length and are short.
- Do not wire other lines near or under the OTG Interface wiring.

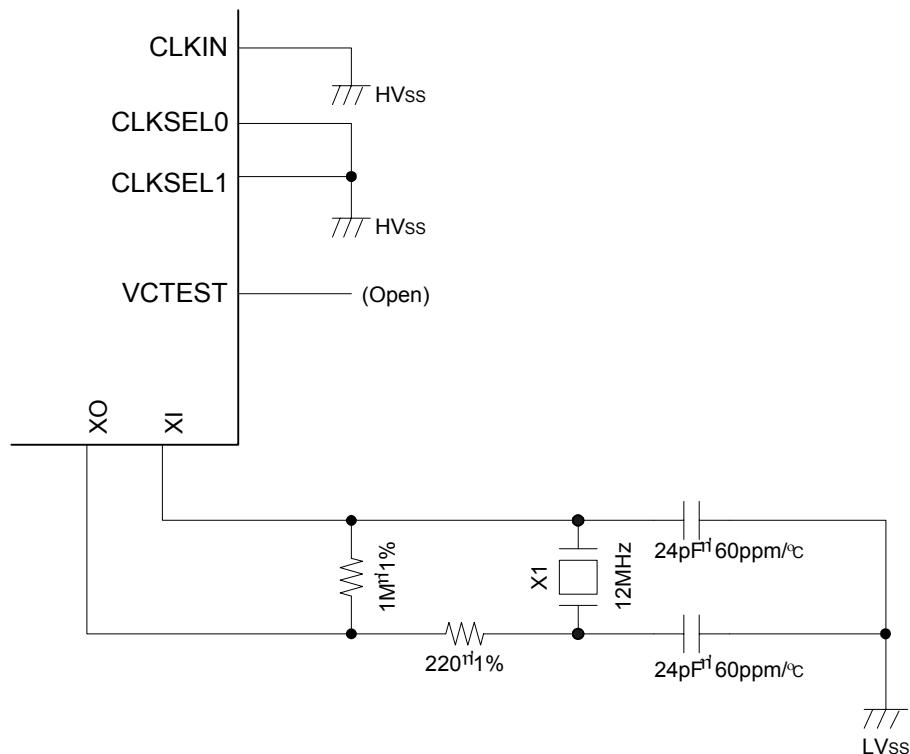
Example of connection parts

(Note) The parts table is for reference only. It does not guarantee operation in your product. Users should select the individual parts carefully.

Section	Symbol	Parts name	Model number	Specification (rating)	Operating temperature (°C)	Manufacturer	Units
1	C1	Ceramic condenser	GRM31MR11C155ZC01	16V 1.5μF	-55 to +125	Murata Manufacturing	1
2	C2	Ceramic condenser	GRM31MF11C475ZA12B	16V 4.7μF	-25 to +85	Murata Manufacturing	1
3	C3	Ceramic condenser	GRM40F104Z50PT	0.1μF	-25 to +85	Murata Manufacturing	1
4	L1, L2	EMI Filter	BLM21PG600SN1	600nH	-55 to +125	Murata Manufacturing	2
5	R1, R2	Resistor	RK73H1JTD33F	33Ω	-55 to +125	KOA	2
6	R3	Resistor	RK73H1JTD2.2kD	2.2kΩ	-55 to +125	KOA	1
7	R4, R6	Resistor	RK73H1JTD100kD	100kΩ	-55 to +125	KOA	2
8	R5	Resistor	RK73H1JTD43kD	43kΩ	-55 to +125	KOA	1
9	R7, R8	Resistor	RK73H2BTD47kF	47kΩ	-55 to +125	KOA	2
10	Q1	FET	TPCS8205		-55 to +150	Toshiba	1
11	Q2, Q3	Transistor	2SA1121	PNP	-55 to +125	Toshiba	2
12	D1, D2	Diode	1SS396		-40 to +100	Toshiba	2
13	D3	Diode	NNCD5.6LG		-40 to +100	NEC	1
14	CN1	USBReceptacle	MNE20	USB miniAB	—	ACON	1

9.2 Clock Pin Connection (Example)

<When using crystal oscillator>

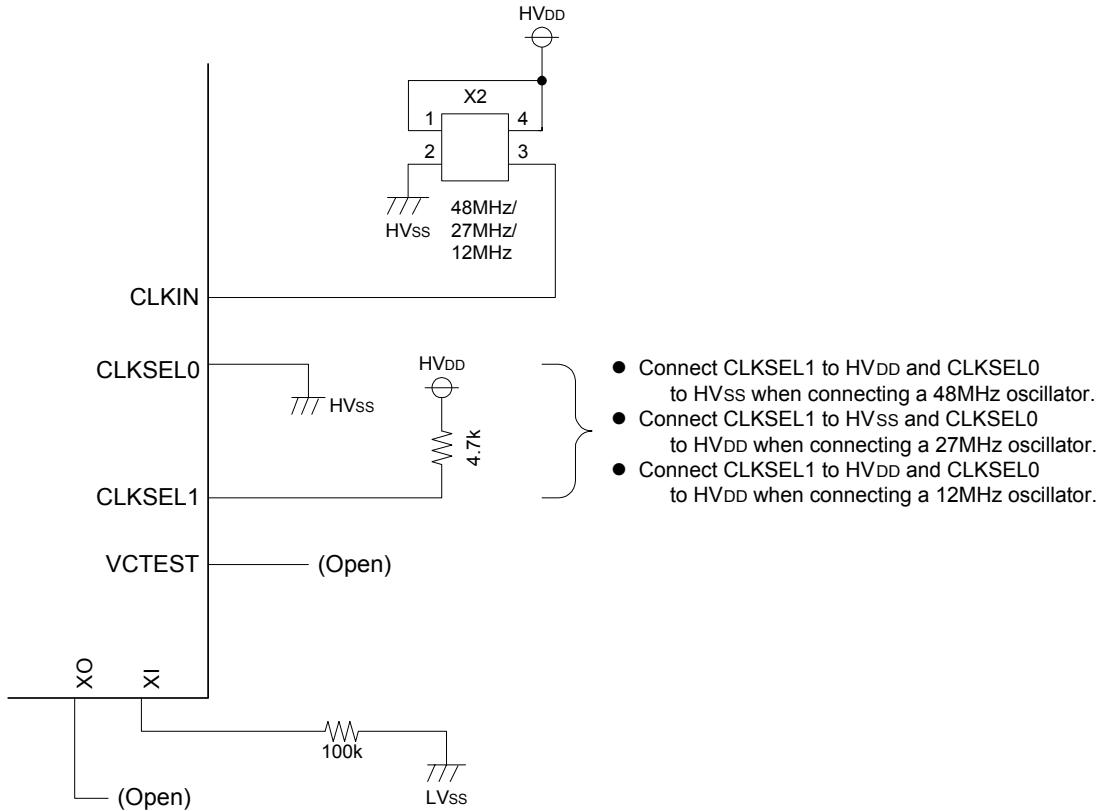


X1*: 12MHz 10pF 30ppm

(Note on connection)

- Do not wire other lines near or under the clock wiring.
- For XI and XO circuits and ratings, refer to connection example for crystal oscillator X1.
- Wire the XI and XO circuits using minimum length of wires.
- Make sure that a disused pattern is not connected to the VCTEST pin.

<When using crystal oscillator (external clock input)>



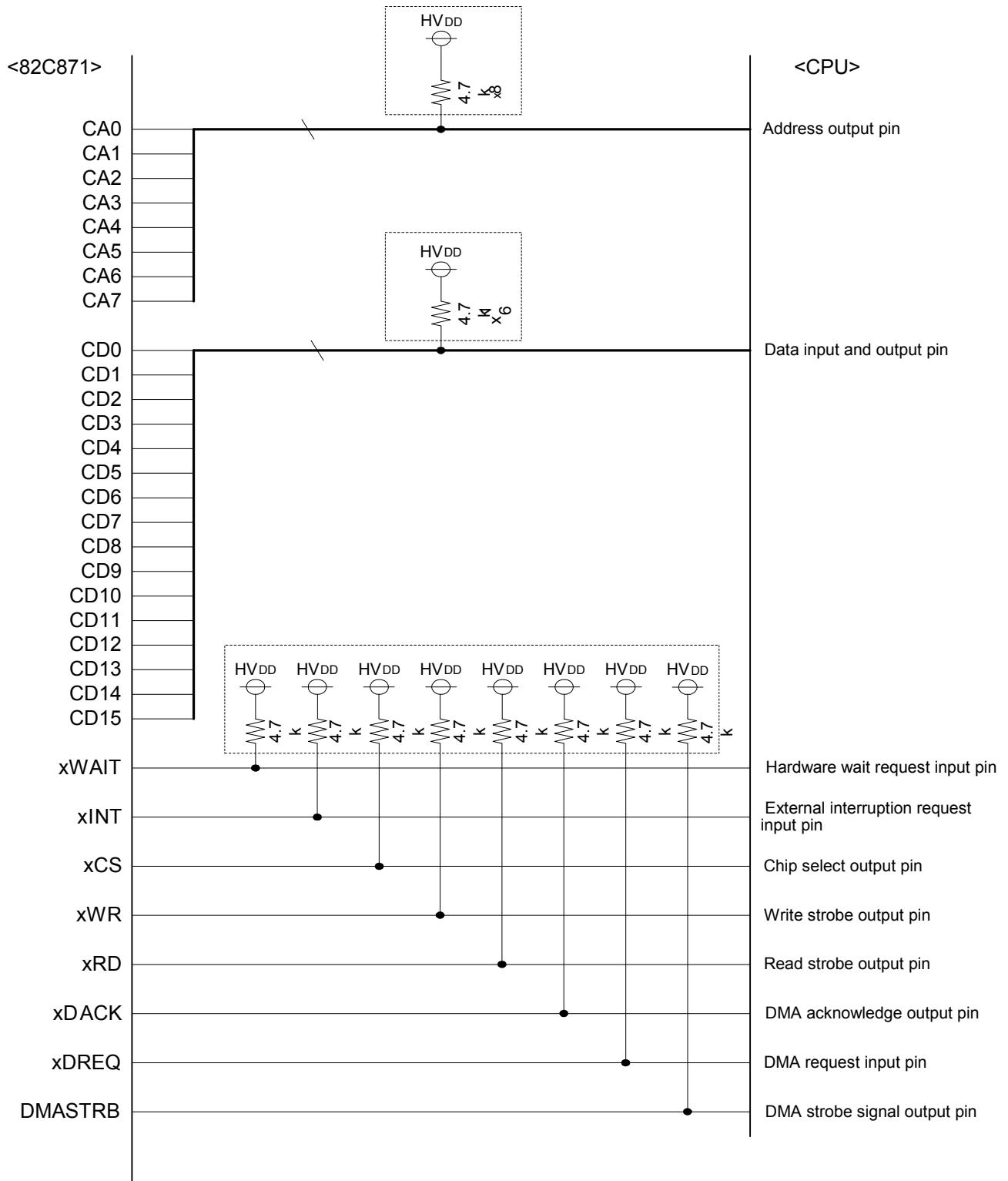
X2*: 48MHz \pm 50ppm

Crystal oscillator of center frequency of \pm 50ppm or lower is recommended.
The PLL device is not recommended due to its high amount of jitter.

(Note on connection)

- Do not wire other lines near or under the clock wiring.
- For CLKIN circuit, refer to connection example for crystal oscillator X2.
- Wire the CLKIN circuit using minimum length of wires.
- Follow the HV1 input voltage standard value of the operation requirement for the CLKIN input voltage.
- Make the XI wiring as short as possible.
- Make the XO wiring as short as possible, and leave it open.
- Make sure that a disused pattern is not connected to the VCTEST pin.

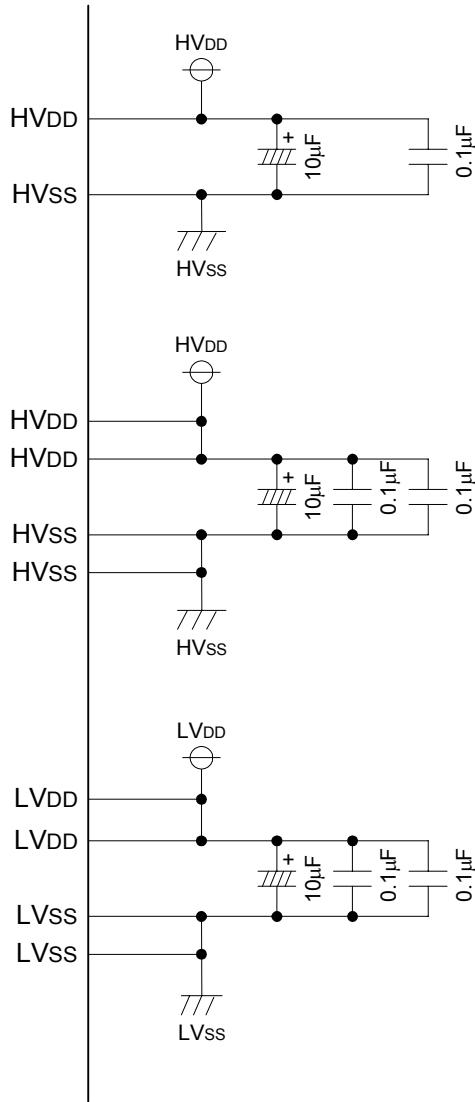
9.3 CPU Interface Pin Connection (Example)



(Note on connection)

- Use the pull up resistor if it is necessary in your system.
- When the 82C871's DMASTRB pin is not used, connect this pin to HVss.

9.4 Power Supply and Ground Pin Connection (Example)



(Caution on connection)

- Use a common grounding for the HVss and the UVss. Also, use the common grounding for the CPU's I/O grounding.
- Connect an exclusive condenser (see the top diagram) for the HVDD (CSP: G3, QFP: 20-pin) and HVss (CSP: H5, QFP: 23-pin) placed on the USB I/O.

9.5 Test Pin Connection (Example)

